ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Par	PC. Bannockł	ourn. Illinois. A	ll rights reserved utions.	under both	This docume level parts, t	ent is a declaration he declaration er	on of the su	bstances v all lower	vithin the manufactur level materials for w	rer listed it hich the m	em. Note:	if the item is an as r has engineering	sembly with low responsibility.
IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
Supplier Information													
Company name* Com			ny unique ID			Unique ID Authority				Response Date*			
nsemi						2024-05-03							
ontact Name		Title - Contac	et]	Phone - Contact	hone - Contact* Email - Contact*						
Product-Env-Stewards Produ			uct Enviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* Title -			sentative	Phone - Representative* Email - Representative*									
Product-Env-Stewards Produ			ro Compliance			NA Product-Env-Stewards@onsemi.com					m		
Requester Item Number Mfr Item		Number Mfr Item Name			Effective Date	Version	М	Manufacturing Site		Weight*	UOM	Unit Type	
		AR0220AT4R00XUE 2MP 1/2 CIS SO A1-DPBM				2024-05-03		Т	TWU		298.74	mg	Each
Ianufacturing Proccess Information	tion												
Terminal Plating / Grid Array Ma	terial 7	Cerminal Base A	Alloy	J-STD-020 MSL	Rating	Peak Proce	ss Body Te	emperature	Max Time at Peak	Temperat	ure Num	ber of Reflow Cyc	les
SnAgCu	(CU Alloy		3		260		С	30	secon	ds 3		
omments													
TTENTION: MSL 3 Rated item require	s Bake and D	ry Pack (after	electrical test)										
or more information regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth						
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
	62.85	mg		Misc.	proprietary data		0.2388	mg
			Supplier	Silicon (Si)	7440-21-3		61.989	mg
			Supplier	Aluminum (Al)	7429-90-5		0.6222	mg
Die Attach	3.83	mg		Bismaleimide Monomer	proprietary data		1.4745	mg
			Supplier	POLY(ETHYLENE GLYCOL) PHENYL ETHER ACRYLATE	56641-05-5		0.0192	mg
			Supplier	2,2-Bis(4-hydroxyphenyl)propane- epichlorohydrin copolymer acrylate	55818-57-0		0.383	mg
			Supplier	Bis(4-tert-butylcyclohexyl) peroxydicarbonate	15520-11-3		0.0192	mg
			Supplier	2,2-dimethyl-1,3-propanediyl dimethacrylate	1985-51-9		0.383	mg
			Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.383	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.0192	mg
			Supplier	Other Additive Agents	Proprietary Data		0.766	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.383	mg
Ероху	1.83	mg	Supplier	Imidazole Addition	68490-66-4		0.549	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.183	mg
			Supplier	Zirconium Dioxide (ZrO2)	1314-23-4		0.183	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.183	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.732	mg
Imaging Lens	55.66	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		2.783	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		2.783	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		2.783	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		2.783	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.2783	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.783	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		2.783	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		38.6837	mg
Mold Compound	72.64	mg		Epoxy resin	proprietary data		18.0147	mg
			Supplier	Other Additive Agents	Proprietary Data		2.3245	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9	_	7.264	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		42.8576	mg

			Supplier	Silica Crystalline (SiO2)	14808-60-7	2.1792	mg
Passivation	0.3	mg	Supplier	Dimethylsilicone	63148-62-9	0.015	mg
			Supplier	Organic pigment	Proprietary Data	0.03	mg
			Supplier	Other Epoxy resins	Proprietary Data	0.255	mg
Solder Ball 49.4	49.42	mg	Supplier	Silver (Ag)	7440-22-4	1.4826	mg
			Supplier	Tin (Sn)	7440-31-5	47.6903	mg
			Supplier	Copper (Cu)	7440-50-8	0.2471	mg
Solder Mask 5.60	5.605	mg		Epoxy resin	proprietary data	0.6726	mg
			Supplier	Acrylate	Proprietary Data	2.1411	mg
			Supplier	Talc	14807-96-6	0.1513	mg
			Supplier	Miscellaneous	Trade Secret	0.2074	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	2.4326	mg
Substrate Copper Foil	4.313	mg	Supplier	Copper (Cu)	7440-50-8	4.313	mg
Substrate - Core Material	21.426	mg		Epoxy resin	proprietary data	4.643	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3	16.783	mg
Substrate Plating-Au	0.371	mg	Supplier	Gold (Au)	7440-57-5	0.371	mg
Substrate Plating-Cu	19.284	mg	Supplier	Copper (Cu)	7440-50-8	19.284	mg
Substrate Plating-Ni	0.891	mg	В	Nickel (Ni)	7440-02-0	0.891	mg
Wire Bond - Au	0.32	mg	Supplier	Gold (Au)	7440-57-5	0.32	mg